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fixed, a laser beam 38 from a laser beam irradiation apparatus (not shown) is focused via a lens 36 onto the bonding member 16 through the mobile side 32 and the lid 14. The focused laser beam is scanned along the bonding member 16 to irradiate it point by point using a scanner (not shown). By the above irradiation, the bonding member 16 is melted, and as a result the case 10 and the lid 14 are welded together via the bonding member 16 and thereby the case 10 is sealed. In the manner as described above, the crystal oscillator module 1 housing a crystal oscillator 12 as shown in Fig. 1 is formed. After the sealing is over, the pressure is released by the pressure apparatus and thereafter the crystal oscillator module 1 is taken out.

Page 16, line 6 to line 19, delete current paragraph and insert therefor:

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Fig. 8 is a view to explain a manufacturing apparatus of a crystal oscillator module according to a fourth embodiment of the present invention. The phase hologram 39 is arranged between the lens 36 and the bonding member 16 so that it can be positioned on the optical axis for precisely adjusting the dimensions of the diffraction light pattern. Now, the distance from the lens 36 to the bonding member 16 is denoted by f , and a distance from the phase hologram 39 to the bonding member 16 is denoted by d , if the phase hologram 39 is moved in the optical axis direction and thereby d/f can be varied, and hence the dimensions of the diffraction light pattern from the phase hologram 39 can be adjusted to fit those of the bonding member 16.

REMARKS

Claims 1-22 are pending. By this Preliminary Amendment, the specification is amended. Prompt and favorable consideration on the merits is respectfully requested.